External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.64787	100.0	1.5
			Subtotal	0.64787	100	1.5
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.58928	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
			Subtotal	1.58944	100	3.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.012	0.03	0.02778
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.0926
	Copper alloy	Copper (Cu)	7440-50-8	39.83518	99.6	92.2296
	Pure metal layer	Silver (Ag)	7440-22-4	0.10799	0.27	0.25002
			Subtotal	39.99517	100	92.6
Adhesive	Polymer	Paraffin wax	8002-74-2	0.19782	20.0	0.458
	Polymer	Epoxy resin system		0.07913	8.0	0.1832
	Filler	Silver (Ag)	7440-22-4	0.71214	72.0	1.6488
			Subtotal	0.98909	100	2.29
Mould Compound	Flame retardant	Zinc Borate	138265-88-0	2.53178	4.46	5.86178
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.10897	9.0	11.8287
	Filler	Silica -amorphous-	7631-86-9	17.59757	31.0	40.7433
	Pigment	Carbon black	1333-86-4	0.30654	0.54	0.70972
	Filler	Silicon Dioxide (SiO2)	14808-60-7	31.22149	55.0	72.2865
			Subtotal	56.76635	100	131.43
Wire	Copper alloy	Copper (Cu)	7440-50-8	0.01209	100.0	0.028
			Subtotal	0.01209	100	0.028
			Total	100.00001	100	231.528

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